N- and P-Channel Enhancement-Mode MOSFET Pair

Features

- ► Integrated GATE-to-SOURCE resistor
- ► Integrated GATE-to-SOURCE Zener diode
- Low threshold
- ► Low on-resistance
- ► Low input capacitance
- ▶ Fast switching speeds
- ► Free from secondary breakdown
- Low input and output leakage
- Independent, electrically isolated N- and P-channels

Applications

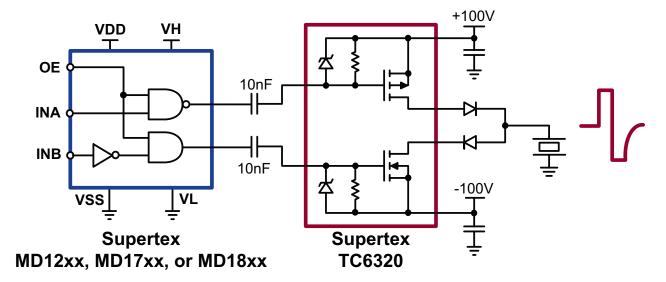
- ► High voltage pulsers
- Amplifiers
- Buffers
- Piezoelectric transducer drivers
- ► General purpose line drivers
- ► Logic level interfaces

General Description

The Supertex TC6320 consists of high voltage, low threshold N-channel and P-channel MOSFETs in 8-Lead SOIC and DFN packages. Both MOSFETs have integrated GATE-to-SOURCE resistors and GATE-to-SOURCE Zener diode clamps which are desired for high voltage pulser applications. It is a complimentary, high-speed, high voltage, GATE-clamped N- and P-channel MOSFET pair, which utilizes an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Typical Application Circuit



Ordering Information

| Part Number | Package Option | Packing | | | |
|-------------|------------------|-----------|--|--|--|
| TC6320K6-G | 8-Lead DFN (4x4) | 3000/Reel | | | |
| TC6320TG-G | 8-Lead SOIC | 2000/Reel | | | |

⁻G indicates package is RoHS compliant ('Green')



Absolute Maximum Ratings

| Parameter | Value |
|-----------------------------------|-------------------|
| DRAIN-to-SOURCE voltage | BV _{DSS} |
| DRAIN-to-GATE voltage | BV _{DGS} |
| Operating and storage temperature | -55°C to +150°C |

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

| Package | $oldsymbol{	heta}_{j_{oldsymbol{a}}}$ |
|-------------|---------------------------------------|
| 8-Lead DFN | 44°C/W |
| 8-Lead SOIC | 101°C/W |

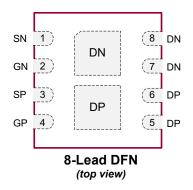
Note:

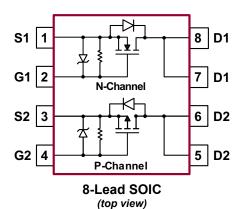
1.0oz, 4-layer, 3"x4" PCB

Product Summary

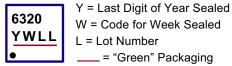
| BV _{DSS} / | /BV _{DGS} /) | $R_{DS(ON)}$ (typ) (Ω) | | | | |
|---------------------|--------------------------|---------------------------------|-----------|--|--|--|
| N-Channel | P-Channel | N-Channel | P-Channel | | | |
| 500 | -500 | 16 | 25 | | | |

Pin Configurations



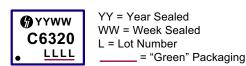


Package Marking



Package may or may not include the following marks: Si or

8-Lead DFN



Package may or may not include the following marks: Si or 🎧

8-Lead SOIC

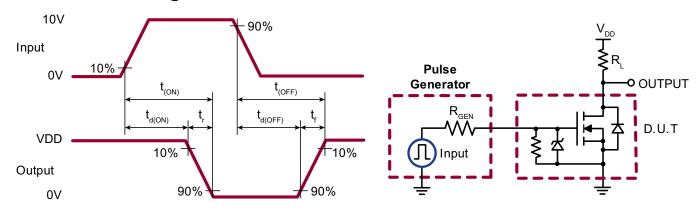
N-Channel Electrical Characteristics (T_A = 25°C unless otherwise specified)

| Sym | Parameter | Min | Тур | Max | Units | Conditions | | |
|---------------------|--|------|-----|------|-------|--|--|--|
| BV _{DSS} | DRAIN-to-SOURCE breakdown voltage | 200 | - | - | V | $V_{GS} = 0V, I_D = 2.0mA$ | | |
| V _{GS(th)} | GATE threshold voltage | 1.0 | - | 2.0 | V | $V_{GS} = V_{DS}$, $I_{D} = 1.0$ mA | | |
| $\Delta V_{GS(th)}$ | Change in V _{GS(th)} with temperature | - | - | -4.5 | mV/°C | $V_{GS} = V_{DS}$, $I_D = 1.0 \text{mA}$ | | |
| R _{gs} | GATE-to-SOURCE shunt resistor | 10 | - | 50 | kΩ | I _{GS} = 100μA | | |
| VZ _{GS} | GATE-to-SOURCE Zener voltage | 13.2 | - | 25 | V | I _{GS} = 2.0mA | | |
| | | - | - | 10.0 | μA | V_{DS} = Max rating, V_{GS} = 0V | | |
| I _{DSS} | Zero GATE voltage DRAIN current | - | - | 1.0 | mA | $V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_A = 125^{\circ}C$ | | |
| ı | On state DDAIN surrent | 1.0 | - | - | ^ | V _{GS} = 4.5V, V _{DS} = 25V | | |
| I _{D(ON)} | On-state DRAIN current | 2.0 | - | - | Α | V _{GS} = 10V, V _{DS} = 25V | | |
| Б | Static DRAIN-to-SOURCE on-state | - | - | 8.0 | 0 | V _{GS} = 4.5V, I _D = 150mA | | |
| R _{DS(ON)} | resistance | _ | - | 7.0 | Ω | V _{GS} = 10V, I _D = 1.0A | | |
| $\Delta R_{DS(ON)}$ | Change in R _{DS(ON)} with temperature | - | - | 1.0 | %/°C | V _{GS} = 4.5V, I _D =150mA | | |
| G _{FS} | Forward transconductance | 400 | - | - | mmho | V _{DS} = 25V, I _D = 500mA | | |
| C _{ISS} | Input capacitance | - | - | 110 | | V _{GS} = 0V, | | |
| C _{oss} | Common SOURCE output capacitance | - | - | 60 | pF | $V_{DS} = 25V,$ | | |
| C _{RSS} | Reverse transfer capacitance | - | - | 23 | | f = 1.0MHz | | |
| t _{d(ON)} | Turn-on delay time | - | - | 10 | | | | |
| t _r | Rise time | - | - | 15 | | V _{DD} =25V, | | |
| t _{d(OFF)} | Turn-off delay time | - | - | 20 | ns | $\begin{vmatrix} I_D = 1.0A, \\ R_{GEN} = 25\Omega \end{vmatrix}$ | | |
| t _f | Fall time | - | - | 15 | | GEN | | |
| V _{SD} | Diode forward voltage drop | - | - | 1.8 | V | V _{GS} = 0V, I _{SD} = 500mA | | |
| t _{rr} | Reverse recovery time | - | 300 | - | ns | V _{GS} = 0V, I _{SD} = 500mA | | |

Notes:

- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

N-Channel Switching Waveforms and Test Circuit



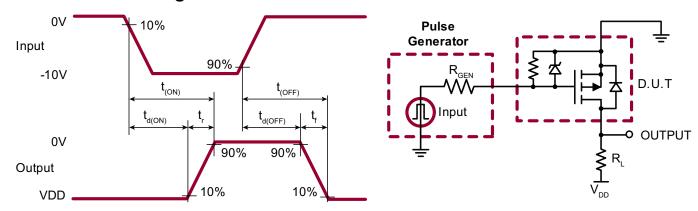
P-Channel Electrical Characteristics (T_A = 25°C unless otherwise specified)

| Sym | Parameter | Min | Тур | Max | Units | Conditions | | |
|---------------------|--|------|-----|------|-------|--|--|--|
| BV _{DSS} | DRAIN-to-SOURCE breakdown voltage | -200 | - | - | V | $V_{GS} = 0V, I_{D} = -2.0 \text{mA}$ | | |
| V _{GS(th)} | GATE threshold voltage | -1.0 | - | -2.4 | V | $V_{GS} = V_{DS}$, $I_{D} = -1.0$ mA | | |
| $\Delta V_{GS(th)}$ | Change in V _{GS(th)} with temperature | - | - | 4.5 | mV/°C | $V_{GS} = V_{DS}$, $I_{D} = -1.0$ mA | | |
| R _{GS} | GATE-to-SOURCE shunt resistor | 10 | - | 50 | kΩ | I _{GS} = 100μA | | |
| VZ _{GS} | GATE-to-SOURCE Zener voltage | 13.2 | - | 25 | V | I _{GS} = -2mA | | |
| | | - | - | -10 | μA | V _{DS} = Max rating, V _{GS} = 0V | | |
| l _{DSS} | Zero GATE voltage DRAIN current | - | - | -1.0 | mA | $V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_A = 125^{\circ}C$ | | |
| | On state DDAIN surrent | -1.0 | - | - | ^ | V _{GS} = -4.5V, V _{DS} = -25V | | |
| I _{D(ON)} | On-state DRAIN current | -2.0 | - | - | A | V _{GS} = -10V, V _{DS} = -25V | | |
| Ь | Static DRAIN-to-SOURCE on-state resis- | - | - | 10 | 0 | V _{GS} = -4.5V, I _D = -150mA | | |
| $R_{DS(ON)}$ | tance | - | - | 8.0 | Ω | V _{GS} = -10V, I _D = -1.0A | | |
| $\Delta R_{DS(ON)}$ | Change in R _{DS(ON)} with temperature | - | - | 1.0 | %/°C | V _{GS} = -10V, I _D =-200mA | | |
| G _{FS} | Forward transconductance | 400 | - | - | mmho | V _{DS} = -25V, I _D = -500mA | | |
| C _{ISS} | Input capacitance | - | - | 200 | | V _{GS} = 0V, | | |
| C _{oss} | Common SOURCE output capacitance | - | - | 55 | pF | $V_{DS} = -25V$, | | |
| C _{RSS} | Reverse transfer capacitance | - | - | 30 | | f = 1.0MHz | | |
| t _{d(ON)} | Turn-on delay time | - | - | 10 | | | | |
| t _r | Rise time | - | - | 15 | | V _{DD} = -25V, | | |
| t _{d(OFF)} | Turn-off delay time | - | - | 20 | ns | $I_{D} = -1.0A,$ $R_{GEN} = 25\Omega$ | | |
| t _f | Fall time | - | - | 15 | | GEN | | |
| V _{SD} | Diode forward voltage drop | - | - | -1.8 | V | V _{GS} = 0V, I _{SD} = -500mA | | |
| t _{rr} | Reverse recovery time | - | 300 | - | ns | V _{GS} = 0V, I _{SD} = -500mA | | |

Notes:

- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

P-Channel Switching Waveforms and Test Circuit



8

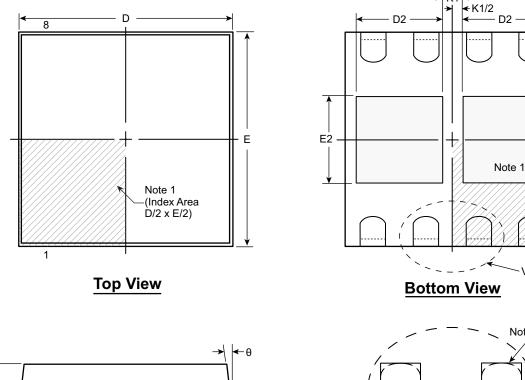
View B

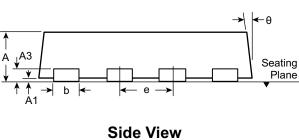
Note 1

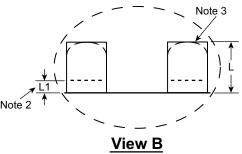
(Index Area D/2 x E/2)

8-Lead DFN Package Outline (K6)

4.00x4.00mm body, 1.00mm height (max), 1.00mm pitch (dual pad)







Notes:

- A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
- 2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
- 3. The inner tip of the lead may be either rounded or square.

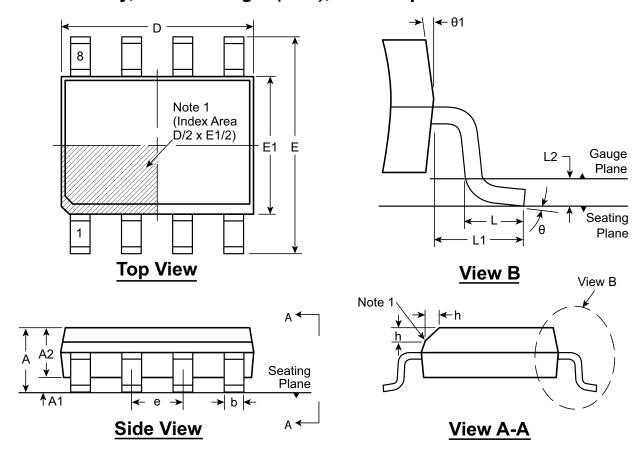
| Symbo | ol | Α | A1 | А3 | b | D | D2 | E | E2 | е | K1 | L | L1 | θ |
|----------------|-----|------|------|-------------|------|------|------|------|------|-------------|-------------|------|------|-----|
| | MIN | 0.80 | 0.00 | | 0.25 | 3.90 | 1.35 | 3.90 | 1.35 | | | 0.40 | 0.00 | 0° |
| Dimension (mm) | NOM | 0.90 | - | 0.20 REF | 0.30 | 4.00 | 1.45 | 4.00 | 1.45 | 1.00 BSC | 0.50 REF | 0.50 | - | - |
| (111111) | MAX | 1.00 | 0.05 | | 0.35 | 4.10 | 1.55 | 4.10 | 1.55 | | | 0.60 | 0.15 | 14º |

Drawings not to scale

Supertex Doc. #: DSPD-8DFNK64x4P100, Version C010813

8-Lead SOIC (Narrow Body) Package Outline (TG)

4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note:

 This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

| Symbo | | Α | A 1 | A2 | b | D | Е | E1 | е | h | L | L1 | L2 | θ | θ1 | |
|----------------|-----|-------|------------|-------|------|-------|-------|-------|-------------|------|----------|-------------|-------------|------------|------------|----|
| | MIN | 1.35* | 0.10 | 1.25 | 0.31 | 4.80* | 5.80* | 3.80* | | | 0.25 0.4 | 0.40 | | | 0 ° | 5° |
| Dimension (mm) | NOM | - | - | - | - | 4.90 | 6.00 | 3.90 | 1.27 BSC | - | - | 1.04 REF | 0.25 BSC | - | - | |
| () | MAX | 1.75 | 0.25 | 1.65* | 0.51 | 5.00* | 6.20* | 4.00* | | 0.50 | 1.27 | | 200 | 8 º | 15° | |

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

Drawings are not to scale.

Supertex Doc. #: DSPD-8SOLGTG, Version I041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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^{*} This dimension is not specified in the JEDEC drawing.

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